

This diagram shows a cross-sectional view of a semiconductor device. It features a central vertical structure with multiple horizontal layers. On the left side, there are four pairs of circular contacts labeled 'DP' and 'TMP', connected by horizontal lines. The device is housed within a multi-layered structure with various internal components labeled with numbers: 7, 137, 201, 135, 130, 120, 140, 202, 115, 157, 150, and 160. Two specific regions are labeled 'CP'.

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